Beverly Display Solutions

Module No.: <u>BD070RDB10</u>

Revision : Ver 1.0

Customer

Approved By	Date	Notes

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1. General Description

• 7.0", Normally Black with Auti-Glare, 16.7M Colors, MVA TFT dot matrix LCD module.

Viewing Angle: 12 o'clock
Logic Voltage: 3.3V(Type)
Data Interface: RGB Interface.

2. Mechanical Specifications

The mechanical detail is shown in Fig. 2 and summarized in Table 1 below.

Table 1

Parameter		Specifications	Unit
Outline dimensions		164.9(W) x 100.0(H) x 5.7(D)	mm
	Active area	154.08(W) x 85.92(H)	mm
Color TFT	Display format	800 (RGB) x 480	dots
240xRGBx320	Color configuration	RGB stripe	-
Dot pitch		0.193 (RGB) (W) x 0.179(H)	mm
Weight		Approx TBD	gram

Note 1: Viewing direction for best image quality is different from TFT definition. There is a 180 degree shift.

Note 2: Requirements on Environmental Protection: Q/S0002

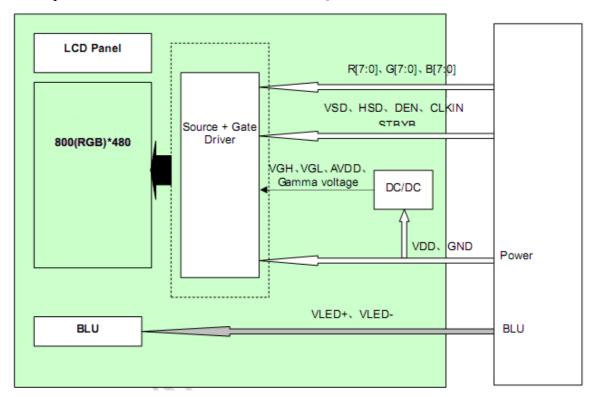
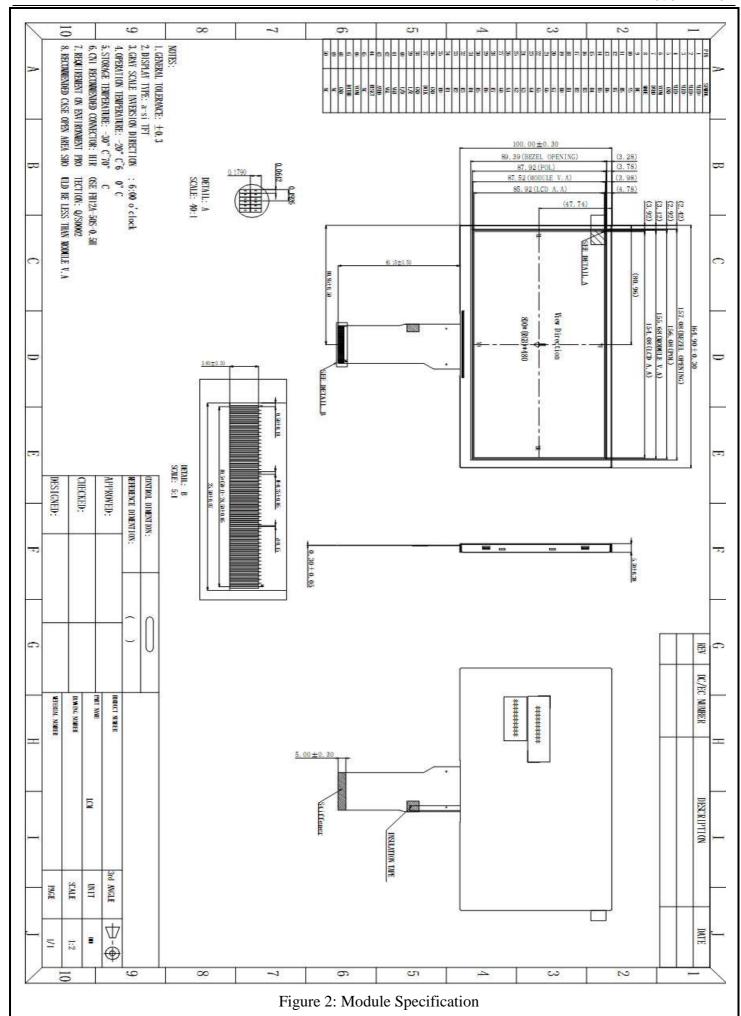


Figure 1: Block Diagram



3. Interface Signals

Table 2: Pin assignment

Pin No.	Symbol	Description
1,2	LEDA	Anode of LED backlight.
3,4	LEDK	Cathode of LED backlight.
5	GND	Ground.
6	Vcom	Common voltage input.
7	VDD	Power supply to the liquid crystal power supply analog circuit. Connect to an external power supply.
8	MODE	DE/SYNC mode select. H: DE mode; L: SYNC mode
9	DEN	Data Enable Signal
10	HSYNC	Horizontal Synchronous Signal
11	VSYNC	Vertical Synchronous Signal
12~19	B7~B0	Blue Data bus.
20~27	G7~G0	Green Data bus.
28~35	R7~R0	Red Data bus.
36	GND	Ground.
37	DCLK	Dot Data Clock
38	GND	Ground.
39	R/L	Set horizontal scan direction. Low/NC: left to right; High: right to left.
40	U/D	Set vertical scan direction. High/NC: up to down; Low: down to up.
41	VGH	Positive power of TFT.
42	VGL	Negative power of TFT.
43	IOVDD	Analog power supply.
44	RESET	Reset signal. Setting either pin low initializes the LSI. Must be reset after power is supplied.
45	NC	Dummy pin, Please let it float.
46	Vcom	Common voltage input.
47	DITHB	Dithering setting. H: 6 bit resolution; L: 8 bit resolution.
48	GND	Ground.
49,50	NC	Dummy pin, Please let it float.

UD/LR Function Description

.		
Scan cont	rol input	Scanning direction
UD	LR	Scanning unection
GND	VCC	Up to down, left to right
VCC	GND	Down to up, right to left
GND	GND	Up to down, right to left
VCC	VCC	Down to up, left to right

4. Absolute Maximum Ratings

4.1 Electrical Maximum Ratings – for IC Only

Table 3

Parameter	Symbol	Min.	Max.	Unit
Power supply voltage (VDD)	IOVDD	-0.5	+15.0	V
Power supply voltage (VDD)	VDD	-0.5	+5.0	V
Back Light Forward Current	IF		50	mA
Logic input voltage	VIN	-0.3	IOVDD+0.5	V
Logic output voltage	VOUT	-0.3	IOVDD+0.5	V

Note 1: GND = 0V.

Note2: No condensation allowed under any condition.

4.2 Environmental Condition

Table 4

Item	Operating temperature (Topr)		Storage temperature (Tstg) (Note 1)		Remark
	Min.	Max.	Min.	Max.	
Ambient temperature(Ta)	-20°C	+70°C	-30°C	+80°C	Dry
	90% max.				
Humidity (Note 1)	RH for Ta	$\leq 40^{\circ} \text{C} < 50\%$	ó		No condensation
Tunnaity (Note 1)	RH for 40°	No condensation			
	operating to				
Vibration(IEC 68-2-6)	Frequency:	$10 \sim 55 \text{ Hz}$			
cells must be mounted	Amplitude:	0.75 mm D	Ouration: 20 o	cycles in each	3 directions
on a suitable connector	direction.				
	Pulse d				
Shock (IEC 68-2-27) Half	Peak ac	3 directions			
-sine pulse shape	Number	5 unections			
	perpendicul	ar axes.		3	

Note 1: Product cannot sustain at extreme storage conditions for long time.

5. Electrical Specifications

5.1 Typical Electrical Characteristics

At Ta = 25 °C, VDD=3.3V, GND=0V.

Table 5

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply voltage	VDD		+3.0	+3.3	+3.6	V
Analog Supply voltage	IOVDD		+9.88	+10.4	+10.92	V
Gate drive High voltage	VGH		14.4	16.0	17.6	V
Gate drive Low voltage	VGL		-7.7	-7.0	-6.3	V
Gate drive Low voltage	Vcom		+3.68	+3.7	+3.72	V
Input signal voltage	V_{IH}	"H" level	0.7VD D	-	VDD	V
	V_{IL}	"L" level	VSS	-	0.3VD D	V
Supply ourrant	ICC+IVDD	VDD= +3.3V, Note1	-	-	30	mA
Supply current	ICC+IVDD	VDD = +3.3V, Note 1	-	-	30	mA
Supply voltage of white LED backlight	VLED	Forward current =160mA(@25°C) Number of LED dies = 24	-	9.6	10.8	V

Note 1: Do not display the fixed pattern for a long time because it may develop image sticking due to the LCD structure. It should change pattern frequently. If the screen is displayed with fixed pattern, use a screen saver.

5.2 TFT Panel Timing Characteristics

5.2.1 Input Setup Timing

At Ta = 25°C, GND=0V, VDD=3.3V.

Parameter	Symbol	Min	Тур	Max	Unit	Remark
DCLK frequency	Fclk	28	30.0	40.0	MHz	
DCLK cycle time	Tcph	25	33.3	36	ns	
DCLK pulse width	Tcw	40%	50%	60%	Tcph	
VS setup time	T _{vst}	8			ns	
VS hold time	Tvhd	8	-	-	ns	
HS setup time	Thst	8			ns	
HS hold time	Thhd	8	-	1	ns	
Data setup time	Tdsu	8			ns	Data to DCLK
Data hold time	Tdhd	8	-	-	ns	Data to DCLK
DE setup time	Tesu	8	-	-	ns	
DE hold time	Tehd	8	-	-	ns	

Table 6

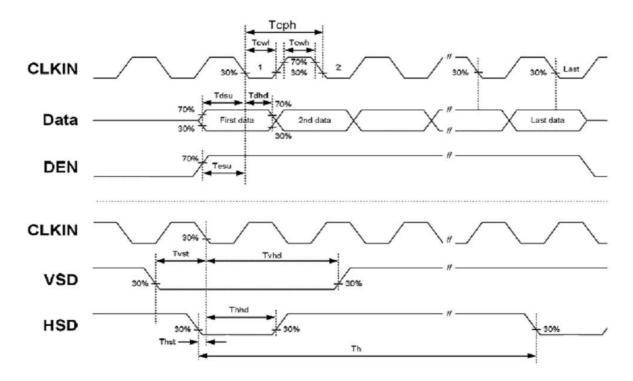


Figure 1: Input Setup Timing

5.2.2 Data Input Timing Parameter Setting

At Ta = 25°C, GND=0V, VDD=3.3V.

Table 7

Parameter	Symbol	Min	Тур	Max	Unit	Remark
DCLK	Fclk	28	30.0	40.0	MHZ	
BOEK	tclk	25.0	33.3	36	ns telk telk	ç.
	th	889	928	1143	tclk	
	thd	800	800	800	tolk	
HS	thpw	1	48	1.	tclk	
110	thb	88	88	88	tclk	c
	thfp	1	40	255	tclk	
	tv	513	525	767	th	
	tvd	480	480	480	th	
VS	tvpw	3	3		th	
	tvb	32	32	32	th	
	tvfp	1	13	255	th	

Note 1: DE timing refer to HS, VS input timing.

TCON Vertical Input Timing Diagram HV

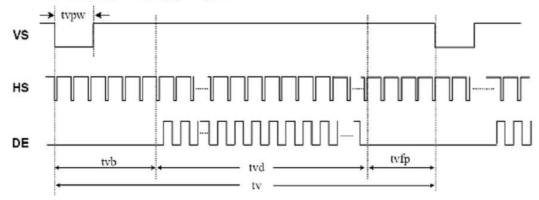


Figure 2: Data Input Timing

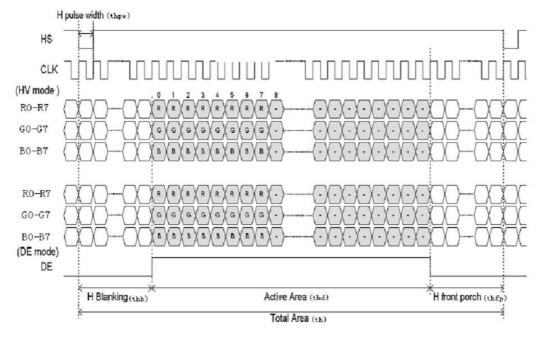


Figure 3: TCON Mode Interface Characteristics

6. Optical Characteristics (for panel only)

Table 8: Optical characteristics

Items		Symbol	Condition		Min.	Typ.	Max.	Unit	Note
Response Time		$T_R + T_F$	Ta=25°C	Viewing normal angle $\theta = \phi = 0^{\circ}$	-	20	30	ms	(Note 1)
	12'	2	Ta=25°C	Center CR≥10	ı	60	-	deg.	(Note 2)
Viewing angle	6'	1			ı	70	-		
	9'	2			-	70	-		
	3'	1			-	70	-		
Contrast Ratio		CR	Ta=25°C	Viewing normal angle $\theta = \phi = 0^{\circ}$	400	500	-	-	(Note 3)
Luminance (on the module surface)		Br	Ta=25°C		280	350	-	cd/m ²	
Transmittance		%			-	6.5	-	%	
	Red	x_R	Ta=25°C	Viewing normal angle θ=φ=0°		0.590		-	(Note 4)
		УR				0.350		-	
Chromaticity	Green	x_G				0.348		-	
		y_{G}				0.580		-	
	Blue	X _B				0.150		-	
		y_{B}				0.100		-	
	White	x_{W}				0.320		-	
		yw				0.340		-	

Note 1: The electro-optical response time measurements shall be made as Figure 5 by switching the "data" input signal OFF and ON. The times needed for the luminance to change from 10% to 90% s $T_{\rm r}$, and 90% to 10% is $T_{\rm f}$.

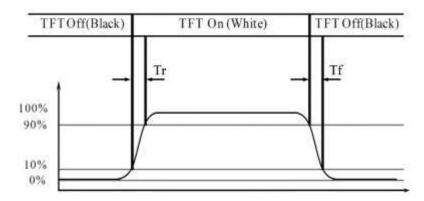


Figure 5: Response Time Testing

Note 2: The definitions of viewing angle.

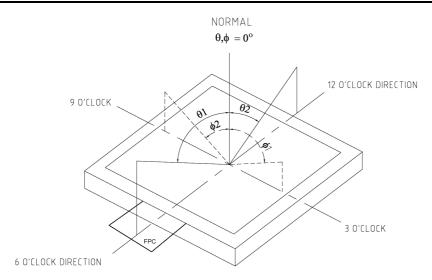


Figure 6

Note 3:Contrast measurements shall be made at viewing angle of θ =0° and at the center of the LCD surface by using DMS. Luminance shall be measured with all pixels in the view field set first to white, then to the dark (black) state. (See figure 6)

Luminace Contrast Ratio (CR) is defined mathematically.

CR = Luminance when displaying a white raster

Luminance when displaying a black raster

Note 4: The color chromaticity coordinates specified in Table 9 shall be updated from later actual spectral data measured with all pixels first in red, green, blue and white. Measurements shall be made at the center of the panel.

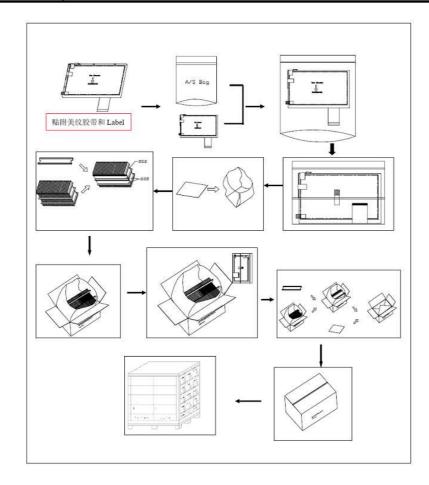
7. TFT Panel Inspection Specifications

F 1 1	T11'	C	otogom (Thite man)	Acceptable count				
Failure mode	Illustration	Ca	ategory(Unit: mm)	Viewing area	non-Viewing area			
	♣ ♦ Width	A	Φ ≦ 0. 10	Not count				
Black spot White spot	Length	В	0. 10<Φ≤0. 15	2, The gap between the two spots should be 5 mm and above.	Not count			
		С	0. 15<Φ≤0. 20	1				
	Φ = (Length+width)/2	D	0. 20< Ф	0				
Bright spot(Red spot,green spot and blue spot caused by damaged colour filter)		A	Area≦1 sub-pixel	1	N/A			
	. W/	A	W≦0.03	Not count	Not count			
Black line	l . ₩	В	$0.03 \le 0.05, L \le 3.0$	2				
White line	L L	С	C 0. 05 <w< td=""><td></td></w<>					
Below are cosn	netic inspection specifications							
Excess glass	b≤1.0, this defect shall not affect the outline dimension or assemb process.(Remarks: For COG process, the defect size is decided by the dimension of LCD panel.)							
Pacess Biggs		This defect shall not affect the outline dimension or assembly process.						
The depth of UV glue entered in LCD cell	D1 W D2	 a. D1≥0.2, not enter into viewing area b. D2≤0.8, c. W=End mouth width + (2~6 mm) 						

	① LCD ledge damage	Category				
	b b	A	The defect shall not affect the outline dimensionassembly process at non ITO zone.			
	W C	В	b≤1/4w, a & c not count (at ITO zone)			
	t	С	Alignment mark on LCD ledge shall not be damaged.			
Glass defect(scratch ,damage)	② Outside of perimeter damage 边框架(Perimeter) 边框内沿(Inside of perimeter) 边框外沿(outside of perimeter)	b can't reach inside of perimeter.				
	③ Joint glass damage 边框架(Perimeter). 边框内沿(Inside of perimeter). 边框外沿(Outside of perimeter).	b can't reach outside of perimeter or ITO layout.				
	4 Corner damage	A	$a \le t$, $b \le 3.0$, $c \le 3.0$			
	b all t	B. Alignment mark on LCD ledge shall not be damaged.				

8. Packing demonstrate

No	Item	Model (Material)	Dimensions(mm)	Unit Weight(Kg)	Quantity	Remark
1	LCM module	BD070RDB10	164.90x100.00x5.7	TBD	50	
2	Partition_1	Corrugated Paper	513x333x215	2.0	1	
3.	Anti-Static Bag	PE	200x175x0.05	0.01	50	Anti-static
4	Dust-Proof Bag	PE	700x545	0.0600	1	
5	Partition_2	Corrugated Paper	505x332	0.1	2	
6	Corrugated Bar	Corrugated Paper	513x148	0.06	4	
7	Beauty-grain	Tape	30x10	TBD	50	,
8	Dessicant	Dessicant	45x35	0.002	8	
9	Carton	Corrugated Paper	530x350x250	1.1000	1	
10	Total weight		TBD±5%			



9. PRECAUTIONS FOR LCM

Beverly Display Solutions LCMs have been assembled and accurately calibrated before delivery. Please observe the following criteria when handling.

9.1 Static electricity warning

A. Do not take the LCM from its anti-static bag until it's to be assembled.

LCM's are individually packaged in bags specially treated to resist static electricity. When storing, keep the LCM packed in the original bags, or store them in a container processed to be resistant to static electricity, or in an electric conductive container.

B. Always use a ground strap when handling a LCM.

Always use a ground strap while working with the module, from the time it is taken out of the anti-static bag until it is assembled. If it is necessary to transfer the LCM, once it has been taken out of the bag, always place it in an electric conductive container. Avoid wearing clothes made of chemical fibers, the use of cotton or conductive treated fiber clothing is recommended.

C. Use a no-leak iron for soldering the LCM.

The soldering iron to be used for soldering the I/O terminals to the LCM are to be insulated or grounded at the iron tip.

D. Always ground electrical apparatuses required for assembly.

Electrical apparatuses required to assemble the LCM into a product, i.e. electrical screw drivers, are to be first grounded to avoid transmitting spike noises from the motor.

- E. Assure that the work bench is properly grounded.
- F. Peel off the LCM protective film slowly.

The module is attached with a film to protect the display surface from contamination, damage, adhesion of flux, etc. Peeling off this film abruptly could cause static electricity to be generated, so peel the tape slowly.

G. Pay attention to the humidity in the work area.

50~60% RH is recommended.

9.2 Precautions for the soldering of a LCM

The following procedures should be followed when soldering the LCM:

- A. Solder only to the I/O terminal.
- B. Use a no leakage soldering iron and pay particular attention to the following:
 - (1) Conditions for soldering I/O terminals

Temperature at iron tip: $280^{\circ}\text{C} + 10^{\circ}\text{C}$

Soldering time: 3~4 sec/terminal

Type of solder: Eutectic solder (rosin flux filled)

Note: (Avoid using flux, because it could penetrate the module and the module may get contaminated during cleaning.) Peel off protective film after soldering the I/O terminals. By following this procedure, the surface contamination caused by the dispersion of flux while soldering can be avoided.

(2) Removing the wiring

(When a lead wire, or a connector to the I/O terminal of the module is to be removed, remove it only after the solder at the connection has sufficiently melted since the I/O terminal is a through hole.) If it is forcefully removed, it could cause the terminal to break or peel. The recommended procedure is to use a suction-type solder remover. Caution: do not reheat the I/O terminal more than 3 times.

9.3 Long-term storage

If the correct method of storage is not followed, deterioration of the display material (polarizer) and oxidation of the I/O terminal plating may make the process of soldering difficult. Please comply with the following procedure.

- A. Store in the shipping container.
- B. If the shipping container is not available, place in anti-static bags and seal the opening.
- C. Store the modules where they are not subjected to direct sunlight or a fluorescent lamp.
- D. Store in a temperature range of 0° C 35 $^{\circ}$ C with low relative humidity.

9.4 Precautions in use of LCD modules

- A. Do not give any external shock.
- B. Do not wipe the surface with hard materials.
- C. Do not apply excessive force on the surface.
- D. Do not expose to direct sunlight or fluorescent light for a long time.
- E. Avoid storage in high temperature and high humidity.
- F. When storage for a long time at 40° C or higher is required, R/H should be less than 60%.
- G. Liquid in LCD is hazardous substance. Do not lick, swallow when the liquid is attached to your hands, skin, clothes etc. Wash it out thoroughly.